

Skyworks Launches Family of Highly Innovative Connectivity Solutions for Smartphones and Tablets

Flip-chip Packaging Significantly Reduces Overall Footprint, Enabling Thinner Solutions for Mobile Platforms

WOBURN, Mass.--(BUSINESS WIRE)-- Skyworks Solutions, Inc. (NASDAQ:SWKS), an innovator of high performance analog semiconductors enabling a broad range of end markets, today unveiled several wireless networking products incorporating flipchip packaging, augmenting its existing world-class mobile connectivity portfolio. Skyworks's newest devices leverage innovative and proprietary manufacturing techniques that allow smartphone and tablet OEMs to incorporate smaller, thinner solutions for 802.11ac system-in-package (SiP) modules. As high-end mobile devices deliver ever-increasing functionality and ubiquitous connectivity, reducing the front-end circuit board footprint is critical as system providers seek high performance, highly flexible solutions for next-generation platforms.



"Skyworks' unique flip-chip packaging capabilities are enabling us to offer unprecedented form factors in support of flagship smartphones and tablets," said Bill Vaillancourt, vice president and general manager of mobile connectivity solutions at Skyworks. "Our newest wireless networking devices are highly integrated and solve our customers' analog and RF complexity challenges so consumers can enjoy mobile platforms with fast, reliable anytime, anywhere data access."

Flip chip is a type of surface mountable packaging technology that reduces footprint and thickness (compared to conventional packaging), weighs less, is easy to assemble, lowers production costs and improves electrical and thermal performance. Flip-chip solutions combine the strengths of various packaging techniques, such as the size and performance advantage of bare die assembly with the reliability of encapsulated devices which can also be fully RF tested at die level. Their significant size and weight reduction makes them ideal for use in a variety of mobile devices including smartphones and tablets.

About Skyworks' Connectivity Solutions

<u>SKY85202-11</u>: a single-pole, triple-throw switch with an integrated LNA for 2.4 GHz, 802.11ac

(Photo: Business Wire) modules

SKY85606-11: a single-pole, double-throw switch with an integrated LNA for 5 GHz, 802.11ac modules

Both devices are highly integrated and feature an LNA with bypass mode, low loss RF switch and DC blocking capacitors in a single, compact flip-chip package. In addition, these Skyworks Green[™] products are compliant with all applicable legislation and are halogen-free.

Additional products in this portfolio will be released later this year.

About Skyworks

Skyworks Solutions, Inc. is an innovator of high performance analog semiconductors. Leveraging core technologies, Skyworks supports automotive, broadband, wireless infrastructure, energy management, GPS, industrial, medical, military, wireless networking, smartphone and tablet applications. The Company's portfolio includes amplifiers, attenuators, circulators, demodulators, detectors, diodes, directional couplers, front-end modules, hybrids, infrastructure RF subsystems, isolators, lighting and display solutions, mixers, modulators, optocouplers, optoisolators, phase shifters, PLLs/synthesizers/VCOs, power dividers/combiners, power management devices, receivers, switches and technical ceramics.

Headquartered in Woburn, Mass., Skyworks is worldwide with engineering, manufacturing, sales and service facilities throughout Asia, Europe and North America. For more information, please visit Skyworks' Web site at: <u>www.skyworksinc.com</u>.

Safe Harbor Statement

This news release includes "forward-looking statements" intended to qualify for the safe harbor from liability established by the Private Securities Litigation Reform Act of 1995. These forward-looking statements include without limitation information relating to future results and expectations of Skyworks (e.g., certain projections and business trends). Forward-looking statements can often be identified by words such as "anticipates," "expects," "forecasts," "intends," "believes," "plans," "may," "will," or "continue," and similar expressions and variations or negatives of these words. All such statements are subject to certain risks, uncertainties and other important factors that could cause actual results to differ materially and adversely from those projected, and may affect our future operating results, financial position and cash flows.

These risks, uncertainties and other important factors include, but are not limited to: uncertainty regarding global economic and financial market conditions; the susceptibility of the semiconductor industry and the markets addressed by our, and our customers', products to economic downturns; the timing, rescheduling or cancellation of significant customer orders and our ability, as well as the ability of our customers, to manage inventory; losses or curtailments of purchases or payments from key customers, or the timing of customer inventory adjustments; the availability and pricing of third party semiconductor foundry, assembly and test capacity, raw materials and supplier components; changes in laws, regulations and/or policies that could adversely affect either (i) the economy and our customers' demand for our products or (ii) the financial markets and our ability to raise capital; our ability to develop, manufacture and market innovative products in a highly price competitive and rapidly changing technological environment; economic, social, military and geo-political conditions in the countries in which we, our customers or our suppliers operate, including security and health risks, possible disruptions in transportation networks and fluctuations in foreign currency exchange rates; fluctuations in our manufacturing yields due to our complex and specialized manufacturing processes; delays or disruptions in production due to equipment maintenance, repairs and/or upgrades; our reliance on several key customers for a large percentage of our sales; fluctuations in the manufacturing yields of our third party semiconductor foundries and other problems or delays in the fabrication, assembly, testing or delivery of our products; our ability to timely and accurately predict market requirements and evolving industry standards, and to identify opportunities in new markets; uncertainties of litigation, including potential disputes over intellectual property infringement and rights, as well as payments related to the licensing and/or sale of such rights; our ability to rapidly develop new products and avoid product obsolescence; our ability to retain, recruit and hire key executives, technical personnel and other employees in the positions and numbers, with the experience and capabilities, and at the compensation levels needed to implement our business and product plans; lengthy product development cycles that impact the timing of new product introductions; unfavorable changes in product mix; the quality of our products and any remediation costs; shorter than expected product life cycles; problems or delays that we may face in shifting our products to smaller geometry process technologies and in achieving higher levels of design integration; and our ability to continue to grow and maintain an intellectual property portfolio and obtain needed licenses from third parties, as well as other risks and uncertainties, including, but not limited to, those detailed from time to time in our filings with the Securities and Exchange Commission.

The forward-looking statements contained in this news release are made only as of the date hereof, and we undertake no obligation to update or revise the forward-looking statements, whether as a result of new information, future events or otherwise.

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Photos/Multimedia Gallery Available: http://www.businesswire.com/multimedia/home/20140310005001/en/

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